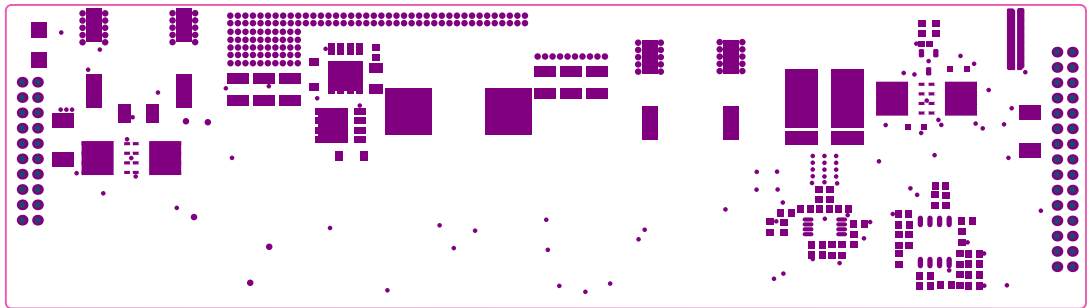
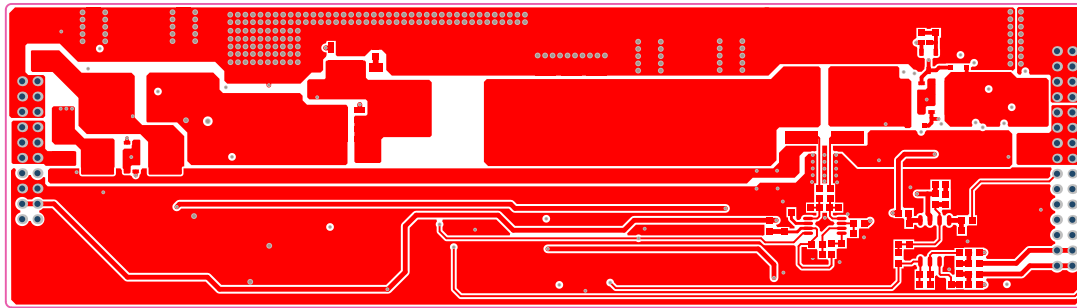


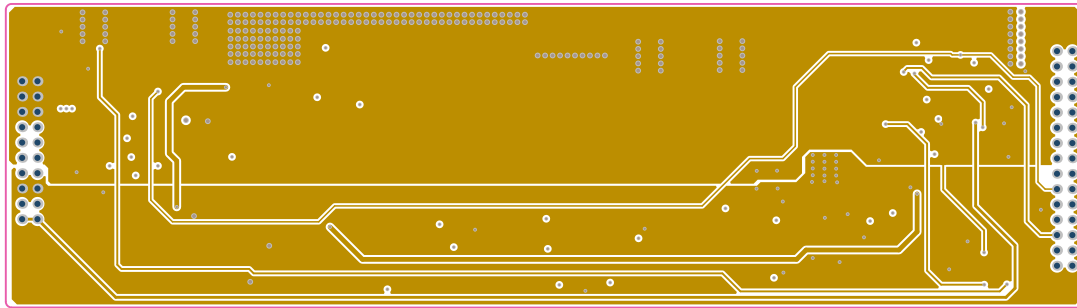
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40182	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP40182		
PLOT NAME = Top Overlay	GENERATED : 2017/4/21	21:08:52	TEXAS INSTRUMENTS



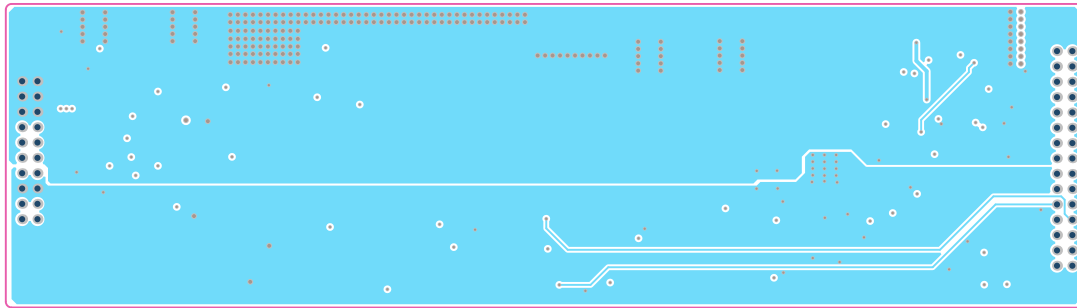
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40182	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP40182		
PLOT NAME = Top Solder Mask	GENERATED : 2017/4/21 21:08:53	TEXAS INSTRUMENTS	



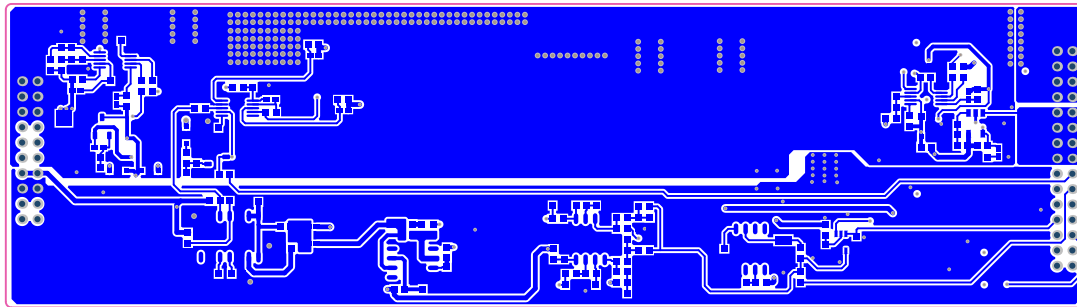
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40182	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP40182		
PLOT NAME = Top Layer	GENERATED : 2017/4/21 21:08:54	TEXAS INSTRUMENTS	



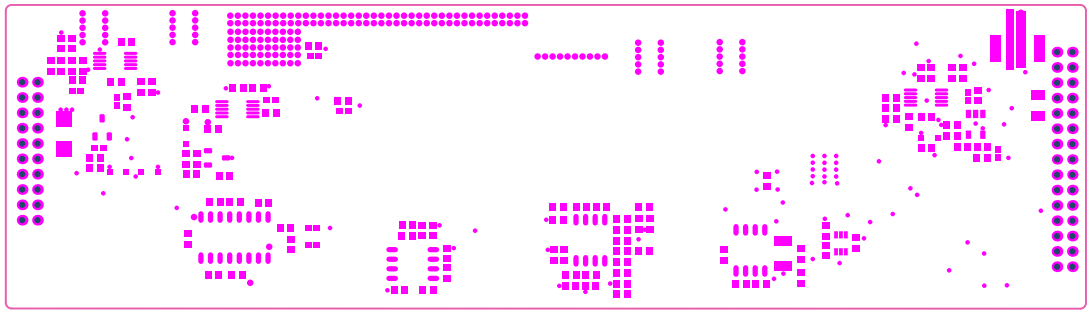
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40182	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP40182		
PLOT NAME = Signal Layer 1	GENERATED : 2017/4/21 21:08:55	TEXAS INSTRUMENTS	



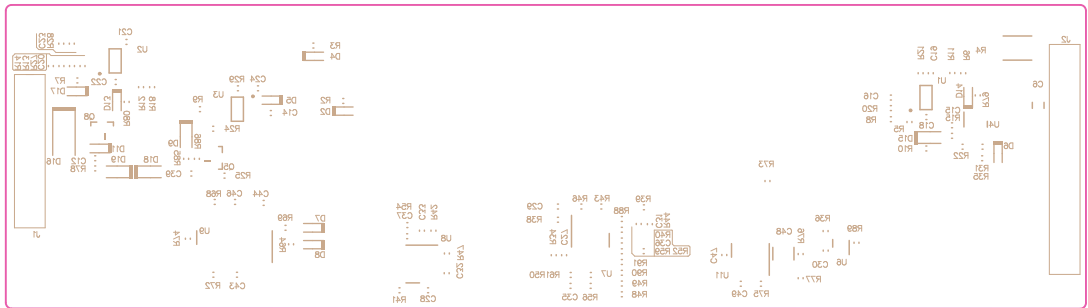
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40182	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP40182		
PLOT NAME = Signal Layer 2	GENERATED : 2017/4/21 21:08:55	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40182	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP40182		
PLOT NAME = Bottom Layer	GENERATED : 2017/4/21 21:08:56	TEXAS INSTRUMENTS	

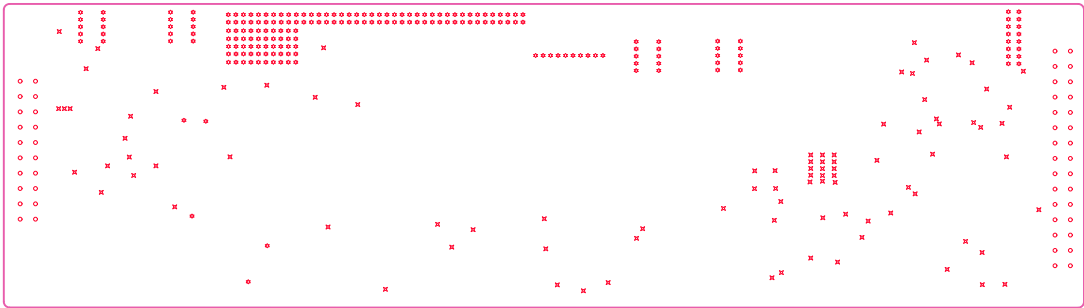


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40182	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP40182		
PLOT NAME = Bottom Solder Mask	GENERATED : 2017/4/21 21:08:57	TEXAS INSTRUMENTS	

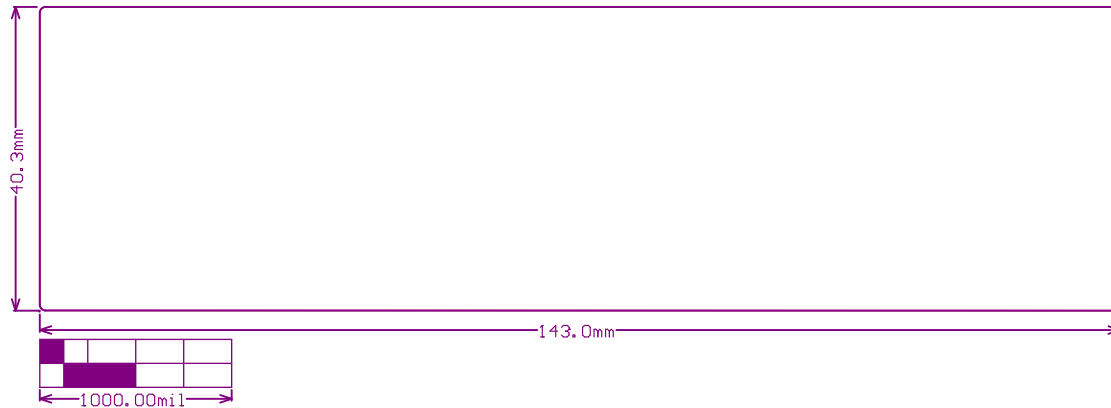


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40182	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP40182		
PLOT NAME = Bottom Overlay	GENERATED : 2017/4/21	21:08:58	TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
X	93	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
☆	201	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
O	50	32.00mil (0.813mm)	PTH	Round	Top Layer - Bottom Layer	
	344 Total					



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40182	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP40182		
PLOT NAME = Drill Drawing	GENERATED : 2017/4/21	21:08:59	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40182	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP40182		
PLOT NAME = Board Dimensions	GENERATED : 2017/4/21 21:09:00	TEXAS INSTRUMENTS	

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